

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16615

Generic Copy

Issue Date: 12-Apr-2011

TITLE: Qualification of Additional Fab and Assembly Source for PACDN042Y3R

PROPOSED FIRST SHIP DATE: 12-Jul-2011

AFFECTED CHANGE CATEGORY(S): Fab Site Change; Package Change; Assembly Site Change

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or <jill.daugherty@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or sales Office or <a href="mailto:

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

This is the final notification announcing that ON Semiconductor is qualifying an additional wafer site and an additional assembly site for PACDN042Y3R product. The additional wafer site will be ON Semiconductor's ISMF fab in Seremban, Malaysia. The additional assembly site will be the Leshan assembly facility in Leshan, China, which is a joint venture between ON Semiconductor and Leshan Radio Company LTD.

The purpose of this change is to qualify a second product source in order to ensure continuous delivery of product to the customer.

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<u>Datasheet change</u>: The marking for device PACDN042Y3R will change from "D052" to "052."

Additional change: The current PACDN042Y3R product uses Au wire. The product from the Leshan facility will use Cu wire.

RELIABILITY DATA SUMMARY:

Reliability Test Results:

Test	Conditions	Results
HTRB	Ta=150C,80% Rated Voltage, 1008 hrs	0/240
Precondition	MSL1@ 260C , 3 X IR at 260 C	0/960
Autoclave+PC	Ta=121C RH=100% ~15 psig, 96 hrs	0/240
HAST+PC	Ta=130C RH=85%, 96 hrs	0/240
	bias=80% rated V or100V Max	
IOL+PC	Ta=25C, Delta TJ = 100 C, 15000 cyc	0/240
	Ton/off = 2 min.	
TC+PC	Ta= -65 C to 150 C, 1000 cyc	0/240
RSH	Ta=260C, 10 sec dwell	0/90
Solderability	Ta=245C, 10 sec dwell	0/30
DPA	Per AEC Q101-004 post TC	0/6
DPA	Per AEC Q101-004 post HAST	0/6

ELECTRICAL CHARACTERISTIC SUMMARY:

Available upon request

CHANGED PART IDENTIFICATION:

Devices with date code marking of 7 or later may be sourced from either factory.

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List of affected General Parts:

PACDN042Y3R

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